

PATENT APPLICATION

Express Mail Label No.: EL 640 011 325 US

IN THE U.S. PATENT AND TRADEMARK OFFICE

May 7, 2001

Applicant(s) : Chikao IKENAGA et al.

For : FRAME FOR SEMICONDUCTOR PACKAGE

Atty. Docket No.: OPS Case 533

Assistant Commissioner for Patents
Washington, DC 20231

AMENDMENT BEFORE FIRST OFFICE ACTION

Sir:

Prior to issuance of the first Office Action in the above-identified application, kindly enter the following:

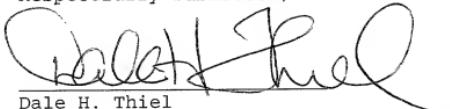
IN THE SPECIFICATION

Kindly amend Paragraphs 0014 and 0015, as indicated on the attached marked-up page. A replacement page, showing Paragraphs 0014 and 0015 in clean form, is also attached.

REMARKS

The above Amendment is being submitted to conform the brief descriptions of Figures 3 and 4 with the drawing sheets.

Respectfully submitted,



Dale H. Thiel

DHT/jp

FLYNN, THIEL, BOUTELL & TANIS, P.C. 2026 Rambling Road Kalamazoo, MI 49008-1699 Phone: (616) 381-1156 Fax: (616) 381-5465	Dale H. Thiel David G. Boutell Ronald J. Tanis Terryence F. Chapman Mark L. Maki David S. Goldenberg Sidney B. Williams, Jr. Liane L. Churney Brian R. Tumm	Reg. No. 24 323 Reg. No. 25 072 Reg. No. 22 724 Reg. No. 32 549 Reg. No. 36 589 Reg. No. 31 257 Reg. No. 24 949 Reg. No. 40 694 Reg. No. 36 328
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Encl: Marked-up Paragraphs 0014 and 0015 (1 page)
Replacement Paragraphs 0014 and 0015 (1 page)

112.9803

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Marked-up Amended Paragraphs 0014 and 0015

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[0014] Fig. 3 is an explanatory view Figs. 3(A) and 3(B) are explanatory views of a frame of individually molding type.

[0015] Fig. 4 is an explanatory view Figs. 4(A) and 4(B) are explanatory views of a frame of collectively molding type.

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Replacement Paragraphs 0014 and 0015

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[0014] Figs. 3(A) and 3(B) are explanatory views of a frame
of individually molding type.

[0015] Figs. 4(A) and 4(B) are explanatory views of a frame
of collectively molding type.